



EtraLED-NIC-7020 Nichia Modular Passive Star LED Heat Sink Ф70mm

Features VS Benefits

- * The EtraLED-NIC-7020 Nichia Passive Star LED Heat Sinks are specifically designed for luminaires using the Nichia LED engines.
- * Mechanical compatibility with direct mounting of the LED engines to the LED cooler and thermal performance matching the lumen packages.
- * For spotlight and downlight designs from 800 to 2,000 lumen.
- * Thermal resistance range Rth 3.70°C/W.
- * Modular design with mounting holes foreseen for direct mounting of Nichia COB series.
- * Diameter 70.0mm standard height 20.0mm, Other heights on request.
- * Forged from highly conductive aluminum.

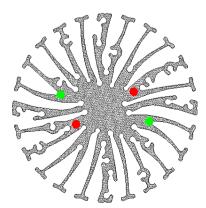
Zhaga LED engine and radiator assembly is a unified future international standardization

- * Below you find an overview of Nichia COB's and LED modules which standard fit on the srar LED heat sinks.
- * In this way mechanical after work and related costs can be avoided, and lighting designers can standardize their designs on a limited number of srar LED heat sinks.









Nichia LED Modules directly Mounting Options

Nichia COB LED modules name:

NFCWL036B;

NFCLL036B; NFCWL060B:

NFCLL060B;

TE LED Holder:2213382-2;

Nichia COB LED modules name:

With the Zhaga Book 11 Holders:

Direct mounting with machine screws M3x8mm, Red indicator marks.

Lena series: CN14xxx; C13xxx; C12xxx; Ronda series: FN15xxx-xx;





Mounting Options and Drawings & Dimensions

Example:EtraLED-NIC-7020-B-1,2

Example:EtraLED-NIC-70 1 -

Height (mm)

Anodising Color

B-Black

C-Clear

Z-Custom

Mounting Options - see graphics for details Combinations available

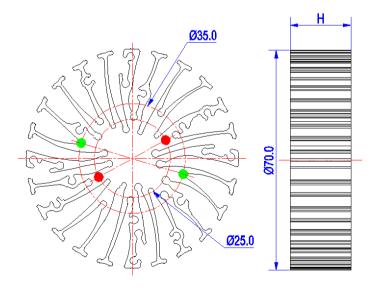
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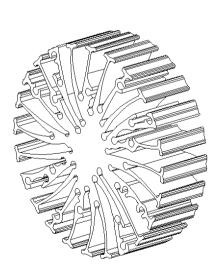
means option 1 and 2 combined

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

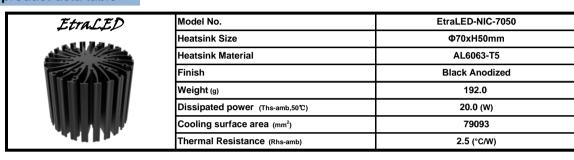
| MOUNTING OPTION | Module type | Holder NO. | LEDiL products | | THREAD | THREAD | THREAD HOLE |
|--------------------|--|------------------------------|--------------------------------|--------------|--------|--------|------------------------------------|
| | | | Lena series | Ronda series | IHKEAD | DEPTH | DISTANCE |
| N | / | None | None | None | None | None | None |
| 1 | NVCWL024Z; NVCLL024Z; NVNWS007Z; NJCWS024Z; | BJB Holder 47.319.6180.50 | CN14xxx; C13xxx; C12xxx; | FN15xxx-xx | МЗ | 6.5mm | 25.0mm/ 2-@180° (Zhaga book 11) |
| | | TE Holder 2213118-1 | | | | | |
| 2 | NFCWL036B; NFCLL036B; NFCWL060B; NFCLL060B; | Ideal Holder 50-2100NC | | | М3 | 6.5mm | 35.0mm/ 2-@180° (Zhaga book 3) |
| | | TE Holder 2213382-2 | | | | | |







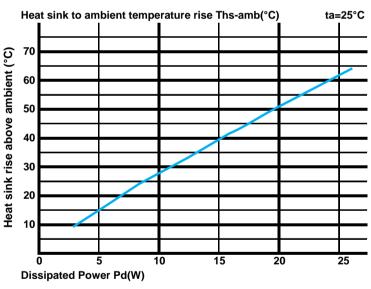
The product deta table



The thermal data table

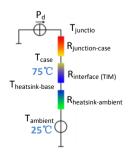
- * Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.
- *To calculate the dissipated power please use the following formula: $Pd = Pe \times (I \eta L)$.
 - Pd Dissipated power ; Pe Electrical power ; $\eta L =$ Light effciency of the LED module;

| Pd = Pe x (1-ηL) | | Heat sink to ambient thermal resistance Rhs-amb (°C/W) | Heat sink to ambient temperature rise Ths-amb (°C) | | |
|------------------------|------|--|--|--|--|
| | | EtraLED-NIC-7050 | | | |
| (M) | 5.0 | 3.00 | 15.0 | | |
| er Pd(| 10.0 | 2.70 | 27.0 | | |
| d Pow | 15.0 | 2.60 | 39.0 | | |
| Dissipated Power Pd(W) | 20.0 | 2.50 | 50.0 | | |
| | 25.0 | 2.44 | 61.0 | | |



- *The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).
- $\label{thm:module} \mbox{MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.}$

 $Either thermal\ grease, A\ thermal\ pad\ or\ a\ phase\ change\ thermal\ pad\ thickness\ 0.1-0.15 mm\ is\ recommended.$



- *Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow. Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths Ta)/Pd$
- θ Thermal Resistance [°C/M]; Ths Heatsink temperature; Ta Ambient temperature;
- *The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface}(TIM)$ ["C,M"], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ ["C,M"], and the ambient temperature is $T_{ambient}$ ["C].
- *Thermal resistances outside the package $R_{interface}$ (TIM) and $R_{heatsink-ambient}$ can be integrated into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used: $T_{iunction} = (R_{unction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$

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